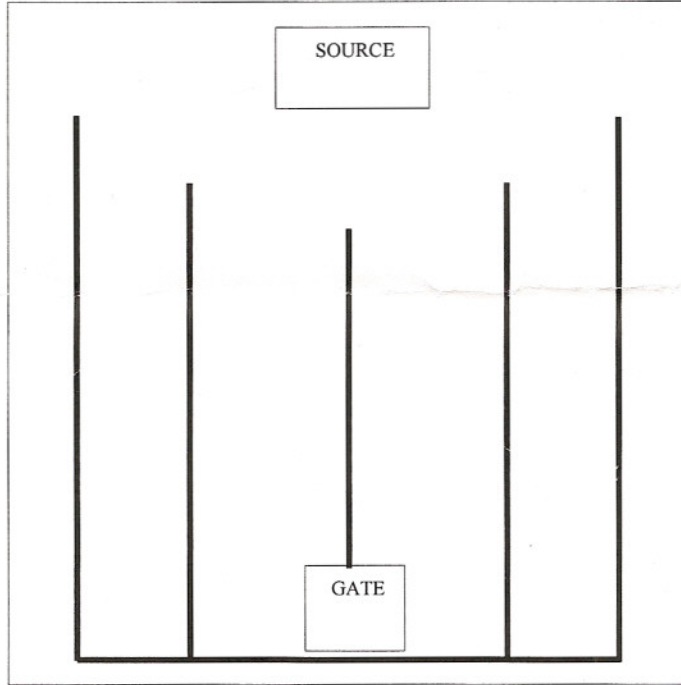




Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947



PAD FUNCTIONS

222 mils

222 mils

CHIP BACK IS DRAIN

The information given is believed to be correct at the time of issue.
 Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
 Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

<p><u>APPROVED</u></p> <p>G Bibby</p> <p>.....</p> <p>DATE: 29 Oct 2003</p>	<p style="text-align: center;">IRFCF40BV</p> <p style="text-align: center;">INTERNATIONAL RECTIFIER</p>	<p><u>DIE INFORMATION</u></p> <p>DIMENSIONS (Mils): 222 x 222 x 18 BOND PADS (Mils): MASK. REF: HEX-2 N-CHANNEL GEOMETRY: BACK POTENTIAL: DRAIN</p>
<p><u>SERIAL NUMBER</u></p> <p>003545</p>		<p><u>METALLISATION</u></p> <p>TOP: Al BACK: CrNiAg</p>